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High-speed Electroplating of Lead-free Solder

Brenda Fernandes & Dr. Kazimierz Wikiel, Technic, Inc., R&D, Cranston, RI

The definite transition toward lead-free electronics brings new challenges for electroplating. Current state-of-the-art tin-lead solder plating technologies must now be replaced by new, lead-free systems. These new technologies must, at least, meet all current requirements and provide comparable performance despite the fact that, in many cases, these systems are thermodynamically unfavorable. This paper describes results of studies on Sn, Sn-Bi, Sn-Cu and Sn-Ag systems. Voltammetric and functional test results will be discussed with special attention for high-speed electroplating.

For more information, contact:
Dr. Kazimierz Wikiel
Technic, Inc.
1 Spectacle Street
PO Box 9650
Cranston, RI 02910
Phone: 401-781-6100
FAX: 401-781-2890
E-mail - kazekw@aol.com